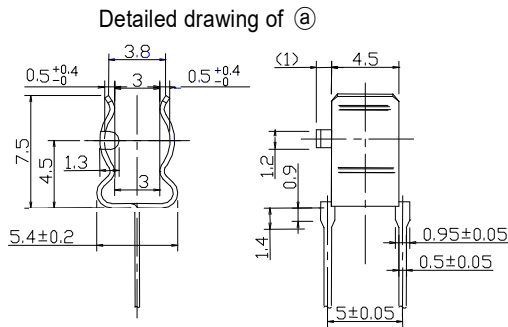




RoHS



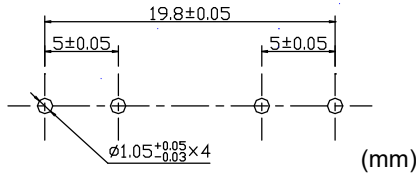
**Dimensions and construction:**



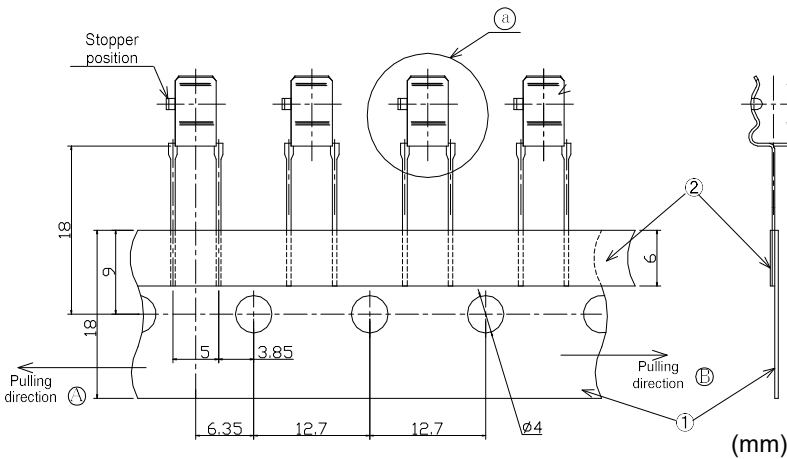
Materials: Copper alloy (TBR-3 1/2H), 0.3 mm thick  
 Surface treatments: Tin plating (Cut surface is not plating)

Dimensional tolerances where not noted	
Dimensional range (mm)	Tolerance ( $\pm$ mm)
$L \leq 3$	0.35
$3 < L \leq 6$	0.45
$6 < L \leq 18$	0.55
$18 < L \leq 30$	0.7
$30 < L \leq 50$	0.9
$50 < L \leq 80$	1.0
$80 < L \leq 120$	1.2

Mounting holes:



**Dimensions of tape**



Pulling direction (A):  
 Stoppers will be placed at the front of the fuse clips.

Pulling direction (B):  
 Stoppers will be placed at the back of the fuse clips. (Pulling direction is marked on the side of the box.)

①: Base paper 0.37 mm thick

②: Adhesive tape

**Characteristics:**

Fuse size:  $\phi 5.2 \times 20$  mm

Rated current: AC/DC 10 A

Insertion/Withdrawal force: 2.5 N–10 N measured using a steel dummy fuse of  $\phi 5.2$  mm

Contact resistance: 2 m $\Omega$  or less when measured by a fall-of-potential method at 100 mA/DC 60 V or by a low ohmmeter, using a copper dummy fuse of  $\phi 5.2$  mm

Solderability: This fuse clip shall satisfy all the requirements specified in JIS C 60068-2-20 when tested as per [the soldering test Ta] Method 1 of the same standard.

**Resistance to soldering heat:**

---

**Wave soldering:**

---

The soldering conditions stated below may be influenced by the material/shape and dimensions of the board, size of the copper foil, and/or heat capacity of the respective components on the board, besides such factors as temperature/duration of preheating, material of solder, temperature of the solder bath, and/or the duration of dipping.

- \* Temperature of molten solder: 260±5 °C
- \* Duration: 10±0.5 s

---

**Hand soldering with soldering iron:**

---

Depending on the components to which the fuse clip is attached (e.g., copper foil on the board) and/or heat capacity of the soldering iron tip, the soldering conditions may vary from those specified below.

- \* Soldering iron tip temperature: 360±10 °C
- \* Duration: 3±0.5 s

Specifications described above are examples when facilities in our company are used. Please make sufficient evaluations under the actual conditions in your company because the conditions may vary depending on facilities, solder type, solder quantity, board size, and board material.

**Usage conditions:**

- \* Ambient temperature:  $-40\text{ }^{\circ}\text{C}$ – $+85\text{ }^{\circ}\text{C}$
- \* Ambient humidity: 85% RH or less

**Storage conditions and storage period:**

Products packaged as delivered can be stored for one year from our shipment under the following conditions.

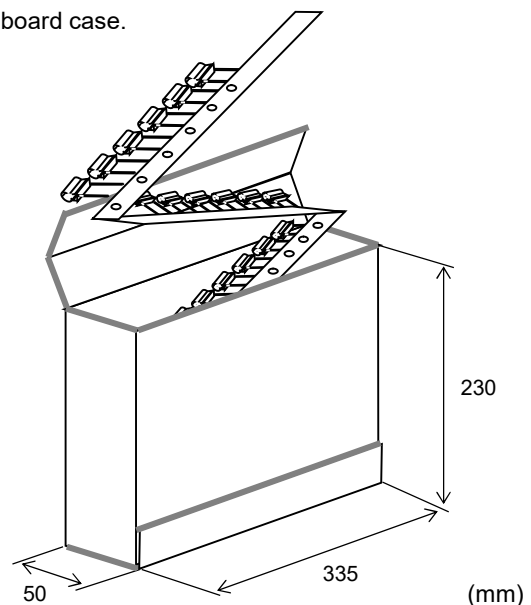
- \* Ambient temperature:  $-30\text{ }^{\circ}\text{C}$ – $+40\text{ }^{\circ}\text{C}$  (no condensation)
- \* Ambient humidity: 85% RH or less
- \* Ambient atmosphere: Not exposed to corrosive gas or sea breeze  
No visible dust  
Not exposed to direct sunlight
- \* Load: No application of load that may cause deformation or degradation of the product.

**Environmental information:**

This product conforms to the EU RoHS Directive 2011/65/EU. The six hazardous substances (lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls [PBB], and polybrominated diphenyl ethers [PBDE]) specified in the EU RoHS Directive are not used intentionally in this product. However, when lead is used in applications exempted from the requirements of the Directive, this will be indicated in the Dimensions and Construction section of the corresponding product specification.

**Packaging:**

1. 1,000 fuse clips are packed continuous fanfold style into cardboard case.
2. An identification label is attached to each cardboard case.
3. The following are indicated on the identification label:
  - \* Product name
  - \* Quantity
  - \* Lot number

**Lot number:**

The lot number indicates the following:

Example: 16012371      160123: Date manufactured  
71:                      Process code

Ordering specifications:

SOC product name: H-0060

Contact information:

SOC is a global ISO-9001 and TS16949 registered company headquartered in Japan with subsidiaries in Asia, Europe, and North America.

SOC Corporation

Marketing Division:

3-16-17, Takanawa, Minato-ku, Tokyo 108-0074, Japan  
TEL +81-3-5420-1011 FAX +81-3-5420-6699  
<http://www.socfuse.com/contact/index.html>

SOC America Inc.:

3505 Veterans Memorial Highway, Suite K-1, Ronkonkoma, NY 11779, USA  
TEL +1-631-472-6666 FAX +1-631-472-6777  
<http://www.socamericainc.com>  
[info@socamericainc.com](mailto:info@socamericainc.com)

SOC Asia Pte. Ltd.:

15 Jalan Kilang Barat, #06-02 Frontech Centre, Singapore 159357  
TEL +65-6376-4115 FAX +65-6376-4117  
[socjp@pacific.net.sg](mailto:socjp@pacific.net.sg)

SOC Europe B.V.:

Databankweg 1, 3821 AL Amersfoort, The Netherlands  
TEL +31-33-450-4000 FAX +31-33-450-4009  
<http://www.soceurope.nl>  
[info@soceurope.nl](mailto:info@soceurope.nl)